

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Wolfgang Hetzel et al.	Examiner:	James M. Mitchell
Serial No.:	10/577,173	Group Art Unit:	2813
Filed:	April 26, 2006	Docket No.:	I441.141.101/QIM4346
Title:	SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING SAME		

AMENDMENT AND RESPONSE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Non-Final Office Action mailed September 3, 2010. Please amend the above-identified patent application as follows: